

**IN THE CLAIMS:**

Claims 1-4 (canceled)

Claim 5 (currently amended): A semiconductor chip ~~as set forth in claim 1,~~  
comprising

a semiconductor substrate having a low impedance portion;

a functional bump provided on a surface of the semiconductor substrate for  
electrical connection between an internal circuit provided on the semiconductor  
substrate and a solid device; and

a dummy bump provided on the surface of the semiconductor substrate and not  
serving for electrical connection between the internal circuit and the solid device yet  
electrically connected to the low impedance portion of the semiconductor substrate,

wherein the functional bump is provided on a peripheral portion of a mating  
surface of the semiconductor chip opposed to the solid device, and

wherein the dummy bump is provided on a central portion of the mating  
surface.

Claim 6 (original): A semiconductor chip as set forth in claim 5, wherein the  
dummy bump has a greater contact area in contact with the solid device than the  
functional bump.

Claims 7-20 (canceled)

Claim 21 (currently amended): A semiconductor device ~~as set forth in claim~~  
19, comprising:

a solid device;  
a semiconductor chip mounted and bonded onto a surface of the solid device;  
a functional bump for electrical connection between an internal circuit of the  
semiconductor chip and the solid device; and  
a dummy bump not serving for electrical connection between the internal  
circuit and the solid device wherein at least one of the solid device and the  
semiconductor chip includes a low impedance portion and the dummy bump is  
electrically connected to the low impedance portion,

wherein the functional bump is disposed in association with a peripheral  
portion of a mating surface of the semiconductor chip opposed to the solid device, and  
wherein the dummy bump is disposed in association.

Claim 22 (currently amended): A semiconductor device ~~as set forth in claim~~  
20, comprising:

a solid device;  
a semiconductor chip mounted and bonded onto a surface of the solid device;  
a functional bump for electrical connection between an internal circuit of the  
semiconductor chip and the solid device; and  
a dummy bump not serving for electrical connection between the internal  
circuit and the solid device wherein at least one of the solid device and the  
semiconductor chip includes a low impedance portion and the dummy bump is  
electrically connected to the low impedance portion,

wherein the functional bump is disposed in association with an active region of the semiconductor chip formed with a functional device,

wherein the dummy bump is disposed in association with a peripheral region surrounding the active region, and

wherein the dummy bump has a greater contact area in contact with the solid device than the functional bump.

Claims 23-31 (canceled).